

氏名	李 偲偲
授与学位	博士 (工学)
学位授与年月日	平成 30 年 3 月 23 日
学位授与の根拠法規	学位規則第 4 条第 1 項
研究科専攻	秋田県立大学大学院システム科学技術研究科 博士後期課程総合システム科学専攻
学位論文題目	Fundamental Investigations on Multi-field Assisted Grinding of Difficult-to-machine Aeronautical Materials (航空難加工材料のマルチフィールド援用研削の基礎研究)
指導教員	教授 <u>尾藤 輝夫</u>
論文審査委員	主査 教授 <u>尾藤 輝夫</u> 副査 教授 <u>鈴木 浩文 (中部大学)</u> 教授 <u>水野 衛</u> 教授 <u>呉 勇波 (南方科技大学)</u>

論文内容要旨

Poor machinability of hard-to-machine materials limits their applications in aircraft industries. From the viewpoint of reductions of cost, it needs a more efficient and productive way to produce these materials. However, the grinding process is brittle material with small size grain, putting it at a disadvantage for large-variety production. In order to improve the grinding ability, one novel hybrid and two multi-filed assisted grinding technologies are proposed and experimental text with hard-to-machine materials in this study. The multi-field assisted machining is combined ultrasonic vibration, electrochemical and plasma electrolytic oxidation into grinding, meanwhile, named them as ultrasonic vibration assisted grinding, ultrasonic assisted electrochemical grinding and ultrasonic assisted plasma oxidation grinding, respectively.

First, the ultrasonic assisted grinding (UAG) apparatus was designed and constructed. An experimental apparatus was established by installing a commercially available ultrasonic spindle onto a commercially available NC grinder through a 3-components piezoelectric dynamometer. The dynamometer was located below the spindle and used for the measurement of grinding forces. In experiments, the workpiece specimen was fixed on a work-holder under which a Z-stage is located for determining the depth of cut. The working surface condition of abrasive tool is one of important issues in grinding process. This article discusses the effects of the ultrasonic vibration on the working surface condition involving chips adhesion and abrasive grains wear during UAG of Inconel 718 with an electroplated cBN grinding wheel as the abrasive tool. In this study, scanning electron microscopic (SEM) observations were performed on the wheel working surface before and after grinding at different vibration amplitudes and the SEM images were filtered, extracted and binarized by using Image-Pro Plus to evaluate the

wheel working surface condition. The obtained results demonstrated that (1) the wear of grinding wheel are dominantly attributed to chips adhesion, grains releasing and grains fracture, (2) both the percentage of chips adhesion area and the size of chips adhered tend to decrease as the vibration amplitude increases; in contrast, the effect of ultrasonic vibration on the number of chips adhesion are not noticeable, (3) the percentage of the number of grains released/fractured decreases as the vibration amplitude rises; e.g., the percentage in UAG at vibration amplitude of $A_{p-p}=9.4\mu\text{m}$ was decreased by 40% compared to that in conventional grinding (CG), (4) higher distribution density of effective cutting edges can be achieved under larger vibration amplitude, and the mean area of effective cutting edges in UAG is smaller than that in CG, demonstrating that the ultrasonication enhances the grinding wheel sharpness.

In order to improve the grindability of Ti-6Al-4V, a multi-field material removal process was proposed in this study. This process was a combination of ultrasonic assisted grinding (UAG) and electrochemical grinding (ECG); hereafter named as ultrasonic assisted electrochemical grinding (UECG). In order to confirm the feasibility of the proposed technique, an experimental setup was constructed and the fundamental machining characteristics of UECG in the grinding of Ti-6Al-4V were experimentally investigated. The results obtained from the investigation summarized as follows: (1) The normal and tangential grinding forces in UECG were smaller than those in conventional grinding (CG) by 60% and 65%, respectively; (2) The work-surface roughness, R_a , both in ECG and UECG decreased with the increasing electrolytic voltage, U_l , and surface damage, such as plastic deformation and cracks, (which often occur in CG) were not observed in UECG; (3) The wheel radius wear in UECG was considerably smaller than that in ECG when $U_l < 10\text{ V}$. The wheel wear in CG was predominantly attributed to the grain drop out, whereas in ECG and UECG the working lives of the wheels were predominantly affected by the chip adhesion and the grain fracture; (4) A 78 nm thick titanium dioxide (TiO_2) layer was generated on the work-surface at $U_l = 20\text{ V}$, and thus the Vickers micro-hardness of work-surface in UECG was lower than that in CG/UAG by 15%; (5) The weight percentages of oxygen elements on chips and work surfaces increased as the U_l increased in ECG and the ultrasonic treatment further enhanced the percentages of oxygen.

Then, the ultrasonic assisted plasma oxidation grinding (UPOG) was investigated. Before material removing, plasma oxidation are important issues in ultrasonic assisted plasma oxidation grinding. In order to investigate grinding parameters to achieve high product quality and productivity, the relation between ultrasonic vibration and plasma oxidation is studied. Effects of grinding parameters (workpiece rotational speed, wheel feed rate, wheel rotational speed, ultrasonic vibration amplitude, and the oscillation frequency), on plasma oxidation are measured. The experiment results show once the plasma voltage was applied, the hardness became decreased. However, when the plasma voltage U_l was beyond 100 V, the plasma discharge intensity became higher locally, which resulted in the formation of melt-quenched, high-temperature oxides on the work surface.

To deeply investigate the material removal mechanism in UPOG of Ti-6Al-4V, the UPOG tests were performed on Ti-6Al-4V. The obtained results evidence that: The grinding forces decreased as the plasma voltage U_l and rotational speed n_g increased. The actual removal depth increased with the increase in input voltage. However, the benefit of the ultrasonication to the grinding efficiency would get smaller when the rotational speed has been set at a larger value. The roughness R_a both in POG and in UPOG decreased with the increasing of U_l and n_g ; the

roughness Ra in UPOG was smaller than that in POG regardless of the process parameters. The UPOG of Inconel 718 was also very effective with high voltage.

The last part of this study is to extend the method on drilling with UPOG so as to open a door to potential industrial applications. The results show that material removal rate in UPOG is deeper than that CG, meaning that material removal is easily achieved in UPOG; high accuracy can be achieved by UPOG.

All in all, this study confirms that UPOG is a highly effective processing method for hard-to-machine material. The technology has the potential to being further extend to other materials.

